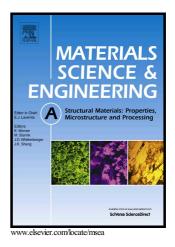
Author's Accepted Manuscript

Enhanced hardness via interface alloying in nanoscale Cu/Al multilayers

X.Z. Wei, Q. Zhou, K.W. Xu, P. Huang, F. Wang, T.J. Lu



 PII:
 S0921-5093(18)30563-X

 DOI:
 https://doi.org/10.1016/j.msea.2018.04.065

 Reference:
 MSA36385

To appear in: Materials Science & Engineering A

Received date: 11 February 2018 Revised date: 13 April 2018 Accepted date: 16 April 2018

Cite this article as: X.Z. Wei, Q. Zhou, K.W. Xu, P. Huang, F. Wang and T.J. Lu, Enhanced hardness via interface alloying in nanoscale Cu/Al multilayers, *Materials Science & Engineering A*, https://doi.org/10.1016/j.msea.2018.04.065

This is a PDF file of an unedited manuscript that has been accepted for publication. As a service to our customers we are providing this early version of the manuscript. The manuscript will undergo copyediting, typesetting, and review of the resulting galley proof before it is published in its final citable form. Please note that during the production process errors may be discovered which could affect the content, and all legal disclaimers that apply to the journal pertain.

Enhanced hardness via interface alloying in nanoscale Cu/Al multilayers

Wei XZ^a, Zhou Q^b, Xu KW^c, Huang P^{c*}, Wang F^{a,d*}, Lu TJ^{a,e}

^aState Key Laboratory for Strength and Vibration of Mechanical Structures Xi'an Jiaotong University, Xi'an 710049, China ^bState Key Laboratory of Solidification Processing, Center of Advanced Lubrication and Seal Materials, Northwestern Polytechnical University, ^cState Key Laboratory for Mechanical Behavior of Material, Xi'an Jiaotong University, Xi'an 710049, China ^dShaanxi Key Laboratory of Environment and Control for Flight Vehicle, Xi'an Jiaotong University, Xi'an 710049, China ^eMOE Key Laboratory for Multifunctional Materials and Structures Xi'an Jiaotong University, Xi'an 710049, China

> huangping@mail.xjtu.edu.cn wangfei@mail.xjtu.edu.cn

*Corresponding authors.

Abstract

Ultrahigh hardness (yield strength) was achieved in magnetron sputtering nanoscale Cu/Al multilayers upon annealing. The microstructure and mechanical properties of the multilayers were systematically investigated by X-ray diffraction, transmission electron microscopy, energy dispersive X-ray spectroscopy and nanoindentation. Annealing promoted diffusion of Cu and Al atoms in the interfaces and the sharp interface turned to mix, resulting in the formation of Cu/Al intermetallic compounds and its deformation at nanoscale. The Cu/Al intermetallic compounds mainly including Al₂Cu grew toward to Al layers and would reducing the effective length between the reduced adjacent layers. As the annealing temperature was increased from 100°C to 500°C, various kinds and larger size Cu/Al intermetallic compounds emerged, causing the hardness to first increase, reaching an unusually high peak (never reached before in other thin metallic multilayer systems), and then remain

Download English Version:

https://daneshyari.com/en/article/7972223

Download Persian Version:

https://daneshyari.com/article/7972223

Daneshyari.com